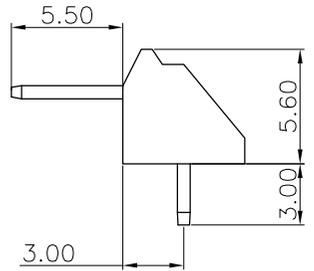
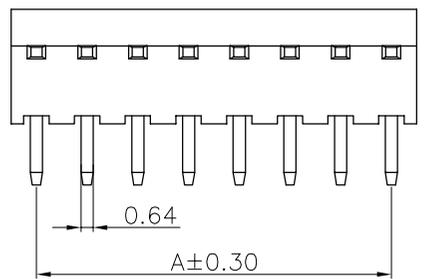
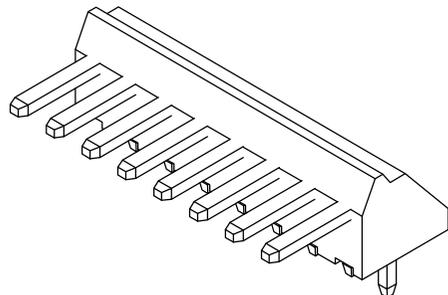
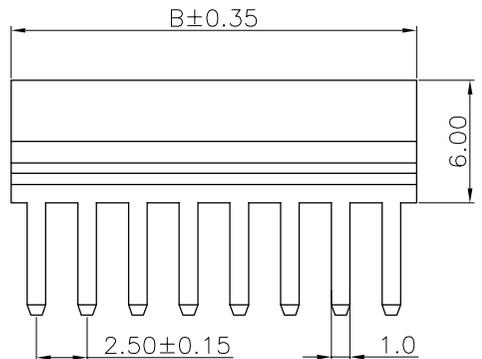


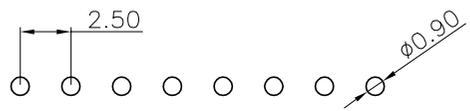
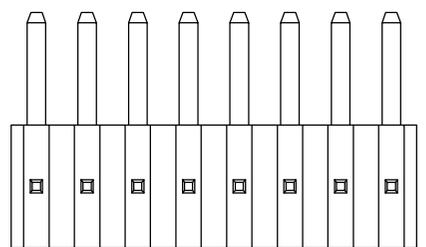
The product using material and processing must conform to the "WI-PZ-001" HSF technical standard control requirements



NOTE:
 1.MATERIAL SPECIFICATION:
 1-1.HOUSING: PA66,UL94V-0
 1-2.CONTACTS: BRASS
 2.PLATING SPECIFICATION:
 2-1.CONTACTS:
 TIN/GOLD FLASH PLATED OVER ALL.
 3.ELECTRICAL PERFORMANCE:
 3-1.CURRENT RATING: 3A AC/DC
 3-2.CONTACT RESISTANCE: 20 mΩ MAX
 3-3.INSULATION RESISTANCE: 1000MΩ Min
 3-4.DIELECTRIC WITHSTANDING : 1500V
 4.ENVIRONMENTAL PERFORMANCE:
 4-1.OPERATING TEMPERATURE: -25°C~+85°C.
 5.PACKAGE SPEC: PE BAG
 6.P/N:



A2504 W 9-1 XX 1 X X X
 SERIES NO: _____ WATER CODE 0-N/A
 CONNECTOR: _____ COLOR: A-BLACK R-RED
 W-WAFER G-BLUE S-NATURE
 ANGLE: _____ PLATING: A-ALL AU G/F
 9-90° C-BRIGHE TIN D-MATTE Tin
 ROW NO: _____ TERMIPOINT: 1-DIP
 1-DOUBLE ROW
 PIN Q'PY: _____
 02~16



PCB Layout

Ordering Information & Dimensions

Circuit	Dimensions(mm)		Circuit	Dimensions(mm)	
	A	B		A	B
02	2.5	5.0	10	22.5	25.0
03	5.0	7.5	11	25.0	27.5
04	7.5	10.0	12	27.5	30.0
05	10.0	12.5	13	30.0	32.5
06	12.5	15.0	14	32.5	35.0
07	15.0	17.5	15	35.0	37.5
08	17.5	20.0	16	37.5	40.0
09	20.0	22.5			

REV.	REVISION RECORD	DATE		GENERAL TOLERANCES		SCALE: 1:1	NAME	DATE	PART.NO:	DWG.NO:	 WanLian Technology Co., Ltd
A0	NEW RELEASE	21.11.17		LINEAR	ANGLES	APPROVED	Wang_jr	23.09.20	A2504W9-1XX1XXX	ENDE05	
A1	PART NUMBER RENEWAL	23.09.20		0.0±0.35	X'REF±6°	DESIGNER	Han_Gao	23.09.20	TITLE:		
				UNIT:mm	X'±3°	DRAWN	Zijun_Huang	23.09.20	2.54 Pitch 90° DIP Single Row Wafer		
			SIZE: A4	0.000±0.10	X'X' ±2°					REV: A1	SHEET: 1/1